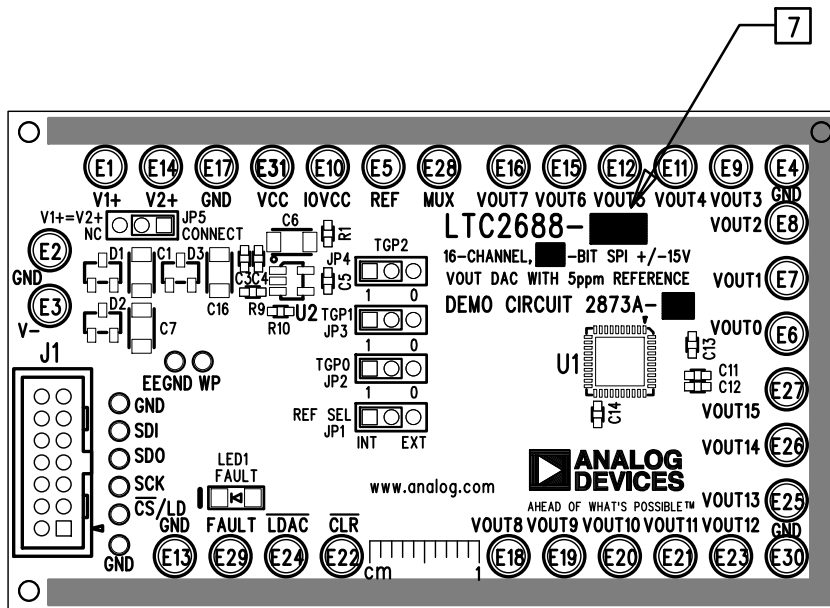



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	CLARENCE M.	04-09-20



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. MARK EACH ASSEMBLY TYPE, SUFFIX, NUMBER OF -BIT IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	SUFFIX	-BIT
A	LTC2688-18	18	18
B	LTC2688-16	16	16
C	LTC2688-12	12	12

APPROVALS		 2555 AUGUSTINE DRIVE SANTA CLARA, CA 95054 www.analog.com	
PCB DES.	KIM T.		
APP ENG.	CLARENCE M.	TITLE: TOP ASSEMBLY DRAWING 16-CHANNEL, 18-/16-/12-BIT SPI +/-15V VOUT DAC WITH 5ppm REFERENCE	
		SIZE N/A	IC NO. LTC2688CUJ-18/-16/-12 DEMO CIRCUIT 2873A
			REV. 2
SCALE = NONE		FILENAME: DC2873A-2.PCB	SHT 1 OF 2